

**Abstract**

Semiconductor die analysis is enhanced via a method and system that use a heater having a plurality of heating elements to heat a selected portion of the die.

According to an example embodiment of the present invention, the heater is thermally  
5 coupled to the die, and the die is operated while at least one of the plurality of heating  
elements heats a portion of the die. A response is detected and used to analyze the die.  
The present invention makes possible selective heating of the die in a manner that is  
readily controllable and implemented. Die analysis, including, for example, critical  
timing path analysis, is enhanced by this ability to controllably heat the die.

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